Wiring, Printed - Component

COMPANY
KSG GmbH
AUERBACHER STR 3-5
GORNSDORF, 09390 Germany

E143060

Type	Cond Min mm	Width Min Edge mm	Cond Thk mic	SS/ DS/ DSO	Max Area Diam mm	Report date After 2022-01-01	Surface Mount Technology	Assembly Solder Process Temp °C	Process Cycles	Solder Limits °C	Solder Limits sec	Max Oper Temp °C	Flame Class	Meets UL796 DSR	CT I
Multilayer (Mass-laminated) printed wiring boards															
MLM	0.15	0.15	30.5	DS	91.4	No	-	-	-	250	8	100	V-0	-	-
Multilayer printed wiring boards															
3M (ASP 1)	0.07	0.11	5 Int:105	DS	90.0	Yes	Yes	260	6	-	-	130	V-0	All	*
4L	0.04	0.06	9 Int:105	DS	50.8	No	-	-	-	288	20	130	V-1	All	*
4M	0.04	0.06	9 Int:105	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
H2 @	0.039	0.117	64 Int:95	DS	25.4	No	-	-	-	288	10	130	V-0	All	3
M10 (ASP 1)	0.04	0.06	5 Int:105	DS	90.0	Yes	Yes	260	6	-	-	130	V-0	All	*
M2	0.064	0.10	9 Int:107	DS	50.0	No	-	-	-	288	20	130	V-0	All	*
M3 (ASP 1)	0.04	0.06	5 Int:105	DS	90.0	Yes	Yes	260	6	-	-	130	V-0	All	*
M4	0.064	0.10	9 Int:107	DS	127.0	No	-	-	-	288	20	130	V-0	All	3
M6 (ASP 1)	0.04	0.06	5 Int:70	DS	50.8	No	Yes	260	6	-	-	130	V-0	All	3
M7 (ASP 1)	0.04	0.06	5 Int:105	DS	90.0	Yes	Yes	260	4	-	-	120	V-0	All	3
M8	0.075	0.10	17 Int:35	DS	50.0	No	-	-	-	288	20	130	V-0	All	*

ML	0.064	0.19	18 Int:107	DS	90.2	No	-	-	-	270	8	125	V-0	All	*
ML1	0.064	0.10	9 Int:107	DS	127.0	No	-	-	-	288	20	125	V-0	All	*
ML2	1.100	1.500	30 Int:18	DS	89.9	No	-	-	-	255	8	125	V-0	All	*
ML3	1.350	1.700	30 Int:400	DS	90	No	-	-	-	230	3	130	V-0	All	*
ML4	0.064	0.100	9 Int:107	DS	127.0	No	-	-	-	288	20	130	V-0	All	3
ML5	0.064	0.10	9 Int:102	DS	127.0	No	-	-	-	288	20	130	V-0	All	*
ML6	0.064	0.190	18 Int:107	DS	90.2	No	-	-	-	270	8	130	V-0	All	*
ML7	0.064	0.190	18 Int:107	DS	13.8	No	-	-	-	270	8	130	V-0	All	3
Multilayer rigid flex composite printed wiring boards, flammability only Recognition															
SF1	-	-	-	DS	-	No	-	-	-	270	10	-	V-0	-	-
SF1<	-	-	-	DS	-	No	-	-	-	270	10	-	V-1	-	-
SF2	-	-	-	DS	-	No	-	-	-	270	10	-	V-0	-	-
SF2<	-	-	-	DS	-	No	-	-	-	270	10	-	V-0	-	-
SF5 (ASP 1)	-	-	-	DS	-	Yes	Yes	260	3	-	-	-	V-0	-	-
SF7	-	-	-	DS	-	No	-	-	-	270	10	-	V-0	-	-
SF7<	-	-	-	DS	-	No	-	-	-	270	10	-	V-1	-	-
Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions intended for use in flexible applications															
SF3 (ASP 1) (Note 2)	0.06	0.10	18 Int:35	DS	50.8	Yes	Yes	260	3	-	-	105	V-0	All	*
SF4 (ASP 1) (Note 2)	0.06	0.10	18 Int:35	DS	50.8	Yes	Yes	260	3	-	-	130	V-0	All	*
Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions intended for use in flexible-rigid applications - Flammability Only Recognition.															
ML-FR1	-	-	-	DS	-	No	-	-	-	288	10	-	V-0	-	-
Multilayer Rigid Flex Composite, Flexible Materials Interconnect Constructions intended for use in flexible-rigid applications.															
ML-FR	0.07	0.07	17 Int:68	DS	60	No	-	-	-	288	10	105	V-0	-	4

(Note 1)															
ML-FR(b) (Note 1)	0.07	0.09	17 Int:68	DS	60	No	-	-	-	288	10	105	V-0	-	-
ML-FR2	0.08	0.24	35 Int:35	SS	60	No	-	-	-	288	10	130	V-0	-	2
SF (Note 1)	0.09	0.09	17 Int:68	DS	60	No	-	-	-	288	20	130	V-0	All	3
Single layer flexible printed wiring boards															
FL	0.1	0.3	17.5	DS	61	No	-	-	-	250	30	105	V-0	-	-
Single Layer flexible printed wiring boards, flammability only Recognition															
FL1	-	-	-	DS	-	No	-	-	-	250	30	-	V-0	-	-
Single layer printed wiring boards															
3D (ASP 1)	0.07	0.11	5	DS	90.0	Yes	Yes	260	6	-	-	130	V-0	All	*
5G	0.04	0.06	9	DS	50.8	No	-	-	-	288	20	130	V-1	All	*
5H	0.04	0.06	9	DS	50.8	No	-	-	-	288	20	130	V-0	All	*
D1	0.064	0.10	9	DS	127.0	No	-	-	-	288	20	125	V-0	All	*
D10 (ASP 1)	0.04	0.06	5	DS	90.0	Yes	Yes	260	6	-	-	130	V-0	All	*
D2	0.064	0.100	9	DS	50.0	No	-	-	-	288	20	130	V-0	All	*
D3 (ASP 1)	0.04	0.06	5	DS	90.0	Yes	Yes	260	6	-	-	130	V-0	All	*
D4	0.064	0.100	9	DS	127.0	No	-	-	-	288	20	130	V-0	All	3
D5	0.064	0.10	9	DS	127.0	No	-	-	-	288	20	130	V-0	All	*
D7 (ASP 1)	0.04	0.06	5	DS	90.0	Yes	Yes	260	4	-	-	120	V-0	All	3
DKL, EEL	0.064	0.19	18	DS	90.2	No	-	-	-	270	8	125	V-0	All	*
DKL2	0.18	0.53	18.3	DS	25.4	No	-	-	-	255	8	120	V-0	All	*
DKL3	0.083	0.25	18.3	DS	90.1	No	-	-	-	270	8	100	V-1	All	0
DKL4	0.064	0.10	9	DS	127.0	No	-	-	-	288	20	130	V-0	All	3
DKL6	0.064	0.19	18	DS	90.2	No	-	-	-	270	8	130	V-0	All	*
S6 (ASP 1)	0.04	0.06	5	DS	50.8	No	Yes	260	6	-	-	130	V-0	All	3
TF1	0.125	0.190	18	DS	89.9	No	-	-	-	288	10	150	V-0	All	0
TF2	0.125	0.190	18	DS	90.1	No	-	-	-	288	10	105	V-0	▲	0

TF3	0.16	0.22	18	DS	89.9	No	-	-	-	288	10	130	V-0	All	0

* - CTI marking is optional and may be marked on the printed wiring board.

ASP 1 - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Assembly Simulation

Note 1 - The copper thickness values shown are for the rigid section. For the flexible section, both internal and external copper are 35 mic only.

Note 2 - External copper thickness of flex part is 18-35mic, external copper thickness of rigid part is 5-102mic, maximum internal copper thickness of rigid part Basefilm is 35mic. Refer to Report for details.

Marking: Company name or tradename "K", "KSG" or trademark , , ,  or file number and type designation. May be followed by a suffix to denote factory identification or flammability classification..

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